Day	Room	7:30 AM	8:00 AM	9:00 AM	10:00 AM	11:00 AM	12:00 PM	1:00 PM	2:00 PM		3:00 PM		4:00 PM	5:00 PM	6 PM	7PM
	Room 1					JC-13 Digital vs. Film Xray TM & Req	IO 40 Ev.O.	G-12 PEM Qual a			ubcommittee	JC-13.1/JC-13 Insertion	.7/G-12 SiC Tech (3:30-5pm)	JC-13.7 Copper	G-12 Terrestrial & Avionics Subcommittee	
Mon 9/28	Room 2 Room 3		JC-13		13.1 MIL-PRF-19500R (Part 1)			Note: JC-13.1 should go to PEMS					Note: JC-13.1 shou go to Copper Wirebond			
								JC-13.5 Pl		PI/()MI 126K (=ralin		JC-13.5 TG172 QMI Requirements				
Day	Room	7:30 AM	8:00 AM	9:00 AM	10:00 AM	11:00 AM	12:00 PM	1:00 PM	2:00 PM		3:00 PM		4:00 PM	5:00 PM	6 PM	7PM
Tues 9/29	Room 1	New Member Orientation	JC-13.2 JEP-121	G-12 Wear-out	JC-13.2 Electronic Parameters & B/I Standardization	JC-13 Underfill Evaluation		JC-13/ G-12 Joint Meeting	G-12 General (meets 2 to 2:30)		Leak Rate Is	C-13 sues in 883 and 750	JC-13 RGA	G-12 & G-11 Counterfeit Mitigation Subcommittee		
	Room 2	JC-13.1 Technical Method Revi			JC-13.1/JC-13.7/G-12 New Technology Appendix in 19500			JC-13.1 MIL-PRF-19500J		J						
	Room 3	om 3		JC-13.5 Subcommittee Meeting			JC-13.5 Packa		age Element Eval	e Element Eval						
	Room 4		JC-13.4 Subcommittee Meeting				JC-13.4 Subcommittee Meeting Topics		g Extended ASTM Meeting							
Day	Room	7:30 AM	8:00 AM	9:00 AM	10:00 AM	11:00 AM	12:00 PM	1:00 PM	2:00 PM		3:00 PM		4:00 PM	5:00 PM	6PM	7PM
Wed 9/30	Room 1			G-12 New Electronic Device	Joint JC-1	3.2/G-12 Meeting		Joint J	C-13.5/G-12 Me	eeting	Jo	int JC-13.1/G-12	Meeting	G-12 & G-11 Spa	ace Subcommittee	
	Room 2		JC-13.1 should	d attend the joint mee	eting with JC-13.4.			JC-13.1 Industry Feedback to DLA: 750 Test Methods and Slash Sheets		dardization of SMD r Packages						
	Room 3 Room 4						J	C-13.2 Meeting			JC-13.5 Meetii	1g				
			Joint G-11 & JC-13.5 Review Element Eval. Req. 38534 G-11 Committee Meeting					Commmittee Meeting		BME	G-11 MIL-STD-1580 Revision					
	Room 5		Joint JC-13.1 & JC-13.4 Subcon						G-12 Radiation RHA Subcommittee							
Day	Room	7:30 AM	8:00 AM	9:00 AM	10:00 AM	11:00 AM	12:00 PM	1:00 PM	2:00 PM		3:00 PM		4:00 PM	5:00 PM	6PM	7PM
Thurs 10/1	Room 1		Joint G-11 / G12 Meeting JC-13 General Session			JC-13 ExCo Meeting (by invitation)										
	Room 2				3-11 Committee Me	eeting										

TG 10-02: Digital vs. Film X-Ray

To Revise the Film and Non-Film Radiography test method standardizing quality and reliability

Draft document ready to be officially balloted and then moved to DLA 750.

POC

TG 11-01: Leak Rate Issues	To revise 883 TM 1014 to improve hermeticity testing, with a focus on packages with the greatest sensitivity.	Document ready to be officially balloted and then moved to DLA	Pat McCord
TG 13-01: RGA review of Proposed Changes to TM1018	·	Draft complete. Document is being sent to DLA for review.	Pat McCord
TG 13-02 : J-STD-002 vs Update of TM2009	To revise TM 2009 or provide inputs to J-STD-002 to improve solderability testing	Decision has been to focus on TM 2009. Draft is close to final before submission to DLA	Lee Mathiesen
TG 13-03: Junction Temperature Requirements	Revising 883 to clarify requirements for ambient and junction temperature for high power devices.	Draft complete. Document is being sent to DLA for review.	Paul Coe
TG 14-01: JEDEC STD Fraudulent/ Counterfeit Parts	To develop a JEDEC standard on supplier actions to mitigate the risk of counterfeit parts in government products	Draft document in ballot	Lee Mathiesen
TG 15-01: Underfill Evaluation	in government products	Early development of task.	Craig Taylor
MIL-STD-750 Test Methods	General review and improvements of test methods for discrete semiconductors	This is an ongoing task group that focuses on maintaining the standard to current conditions.	Chris Velador
MIL-PRF-19500R	General review and improvement of the base standard for discrete semiconductors	This is an ongoing task group. Once one revision to 19000 comes out, they begin work on another.	Beth Parker
New Technology Appendix in 19500	Develoment of general for new technology insertion into mil standard discrete semiconductors	An early draft has been prepared and is being worked.	Chris Velador
SiC Tech Insertion	Development of quality, reliability, and test methods requirements for SiC technology in gov, space, and aerospace electronics	This project is pretty early. Research from ARL is being reviewed for development of appropriate test plans.	Ron Green
MIL-PRF-19500P Appendix J on Non- Hermetics (formerly Appendix F)	Development of requirements for non-hermetic discrete semiconductors in non-space environments.	In working task group	Paul Syndergaard
Standardization of SMD Carrier Packages	This task group focuses on standardizing SMD carrier packages which at this time fall under unique SCD's for qualification	In working task group	Chris Velador
	Development of a JEDEC guideline for	A duesti has been assessed and belleted. Edite and being made a nearly of	
TG2011-01: SMD Electricals/Burn-In Requirement	standardizing parameter selection, deltas, and specific burn-in protocols. Contains background information on why certain techniques are required.	A draft has been prepared and balloted. Edits are being made a result of the ballot. The task group will remain open to begin working on REV A as soon as REV - is released.	Brent Rhoton
TG2013-01: Review of JEP121		Final review is scheduled for May 2015 meeting in Savannah.	Lee Mathiesen
TG 158-104: Review of MIL-PRF-38534	Pavious and undate element avaluation requirements of MIII		
Element Evaluation Requirements	Review and update element evaluation requirements of MIL- PRF-38534.	In working task group	Evon Bennett

TG 169-101: Sub-Assembly element evaluation	Incorporate sub-assembly element evaluation into MIL-PRF-38534.	At DLA for incorporation into MIL-PRF-38534	
TG 172-510: QML requirement review	To define the rework processes for qualification for each of the key rework processes and implement as part of Section C.7 for Appendix C of MIL-PRF-38534.	In working task group	Cora Gustason
TG 173-512: Package Element Evaluation Review	Clarify the requirements, consider adding an option to seal packages, add temperature cycle as an option to thermal shock, reduce salt test qty and add the new lead Integrity test conditions.	Going to ballot after the Jan 2015 meeting	Minh Tran
TG 174-912: Open Architecture Hybrid/Multichip Module	MIL-PRF-38534 addition to an Open Architecture package technology to utilize passives mounted outside a hermetically seal package. Update Appendix D to incorporate changes	Appendix approved and will be forwarded to DLA for incorporation into MIL	-PRF-38534
TG 175-115: MIL-PRF-38534 PI/QML Review and Update	To evaluate the PI and QML columns in tables C.X.c and E-1 to determine if the PI test sequence should be modified with a sequence identical to or similar to the QML test sequence. The TG will also consider periodically requalifying manufacturing processes.	This is a new task group established in January 2015.	Stacy Irwin
Copper Wire Bonds	Development of industry guidelines, and possible input to government standards, for use and test of copper wire bonds.	This is a new task group. They are gathering research on copper wire bonds and devleoping their approach.	Jeff Jarvis
TG PEMS Test Flow	Development of industry guidelines or standars for testing PEMS for government and military applications (focusing on situations where the part is used within its datasheet limits).	There are two teams working in parallel, one on space flows and one on terrestrial flows. Both groups are expected to have complete drafts in 2015.	Sultan Lilani
TG Long Term Storage	Revise GEIA-STD-0003. Possibly develop sister guidelines on refresh / relife testing of older parts, not necessarily stored in dry nitrogen.	Revision of GEIA-STD-0003 is almost complete. It is expected to go to ballot in 2015. Team is still deciding if there is enough interest in the sister document.	
TG Wear-out	Development of industry guidelines on performing and assessing wear-out (long term reliability) assessments of ICs. This is a more detailed "how to" in conjunction with some general requirements being developed by APMC Committee.	This is a new task group. They are currently collecting existing guidelines and relevant research.	Anduin Touw
TG BME	Development on a new mil-prf spec on BME and other very thin film capacitors.	Draft MIL-PRF-THIN was balloted in late 2015. Comments are being reviewed and the document is expected to be handed over to DLA for final coordination in early 2015. The task team will then transition to beginning to develop the first slash sheets for the MIL-PRF.	Anduin Touw